

**Amendments to the Specification**

Please replace the paragraph beginning on page 4, line 13, of the specification with the following amended paragraph:

FIGS. 3A-3[[B]]C are diagrams showing the CEC without a cover.

Please replace the paragraph beginning on page 6, line 18, of the specification with the following amended paragraph:

FIGS. 2 and 3A-3[[B]]C are diagrams illustrating the CEC in further detail. The CEC 20 is supported by a base plate 34 on which high-density connectors 30, processor 36, and memory 38 are mounted. An airtight cover 40 covers the processors 36, but not the memory 38. The fan in the thermal subsystem 26 creates a negative pressure drop, creating an airflow from the air intake 42 in the front of the CEC 20 to the air exhaust 44 over the memory 38. FIGS. 3A-3[[B]]C show the CEC 20 with the cover 40 removed.